INTEGRATED CIRCUITS

DATA SHEET

74F20Dual 4-input NAND gate

Product specification

1989 Mar 03

IC15 Data Handbook





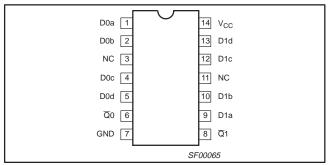
74F20

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F20	3.5ns	2.2mA

ORDERING INFORMATION

DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V $\pm 10\%$, T_{amb} = 0°C to +70°C	PKG DWG #		
14-pin plastic DIP	N74F20N	SOT27-1		
14-pin plastic SO	N74F20D	SOT108-1		

PIN CONFIGURATION

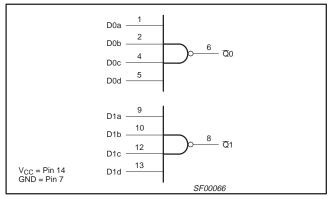


INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dna, Dnb, Dnc, Dnd	Data inputs	1.0/1.0	20μA/0.6mA
<u>Q</u> 0, <u>Q</u> 1	Data outputs	50/33	1.0mA/20mA

NOTE: One (1.0) FAST unit load is defined as: 20μA in the High state and 0.6mA in the Low state.

LOGIC DIAGRAM



FUNCTION TABLE

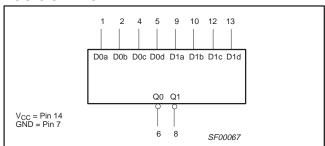
	INP	UTS		OUTPUT
Dna	Dnb	Dnc	Dnd	Qn
L	Х	Х	Х	Н
Х	L	Х	Х	Н
Х	Х	L	Х	Н
Х	Х	Х	L	Н
Н	Н	Н	Н	L

NOTES:

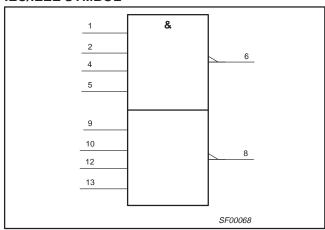
H = High voltage levelL = Low voltage level

X = Don't care

LOGIC SYMBOL



IEC/IEEE SYMBOL



74F20

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in High output state	−0.5 to V _{CC}	V
I _{OUT}	Current applied to output in Low output state	40	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		UNIT		
STWIBUL	PARAMETER	MIN	NOM	MAX	UNII
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V
V _{IL}	Low-level input voltage			0.8	V
I _{IK}	Input clamp current			-18	mA
I _{OH}	High-level output current			-1	mA
I _{OL}	Low-level output current			20	mA
T _{amb}	Operating free-air temperature range	0		+70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

OVMDOL	DADAMETED	TEGT CONDITIO	TEST CONDITIONS ¹				UNIT	
SYMBOL	PARAMETER	TEST CONDITIO	TEST CONDITIONS			MAX	UNII	
V	Lieb level cutout veltere	V _{CC} = MIN, V _{IL} = MAX	MAX ±10%V _{CC} 2.5				V	
V _{OH}	High-level output voltage	$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V	
V	Low lovel cutout valtage	V _{CC} = MIN, V _{IL} = MAX	±10%V _{CC}		0.30	0.50	V	
V _{OL}	Low-level output voltage	$V_{IH} = MIN, I_{OL} = MAX$	±5%V _{CC}		0.30	0.50	V	
V _{IK}	Input clamp voltage	$V_{CC} = MIN, I_I = I_{IK}$	$V_{CC} = MIN, I_I = I_{IK}$			-1.2	V	
I _I	Input current at maximum input voltage	$V_{CC} = MAX, V_I = 7.0V$			100	μΑ		
I _{IH}	High-level input current	$V_{CC} = MAX, V_I = 2.7V$	$V_{CC} = MAX, V_I = 2.7V$			20	μΑ	
I _{IL}	Low-level input current	$V_{CC} = MAX, V_I = 0.5V$	$V_{CC} = MAX, V_I = 0.5V$			-0.6	mA	
los	Short-circuit output current ³	V _{CC} = MAX	V _{CC} = MAX			-150	mA	
	Supply current (total)	V _{CC} = MAX	V _{IN} = GND		0.9	1.4	mA	
Icc	Supply current (total)		V _{IN} = 4.5V		3.4	5.1	IIIA	

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

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All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, IOS tests should be performed last.

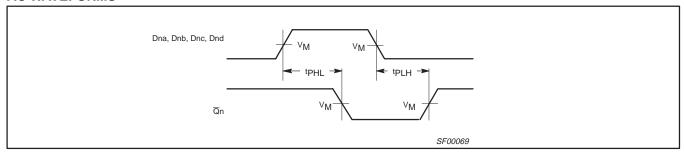
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SF00006

AC ELECTRICAL CHARACTERISTICS

			LIMITS					
SYMBOL	PARAMETER	TEST CONDITION	Ta	CC = +5.0 amb = +25° 50pF, R _L =	C	V _{CC} = +5. T _{amb} = 0°0 C _L = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	1 1
t _{PLH} t _{PHL}	Propagation delay Dna, Dnb, Dnc, Dnd to $\overline{\mathbb{Q}}$ n	Waveform 1	2.4 2.0	3.7 3.2	5.0 4.3	2.4 2.0	6.0 5.3	ns

AC WAVEFORMS

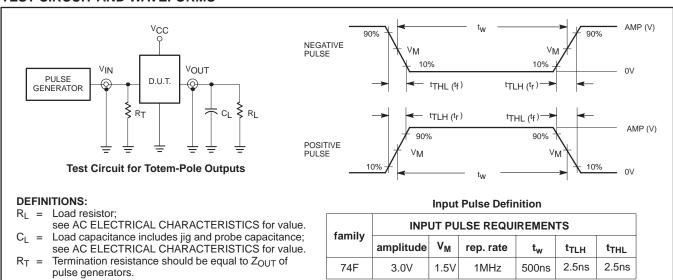


Waveform 1. Propagation Delay for Inverting Outputs

NOTE:

For all waveforms, $V_M = 1.5V$.

TEST CIRCUIT AND WAVEFORMS



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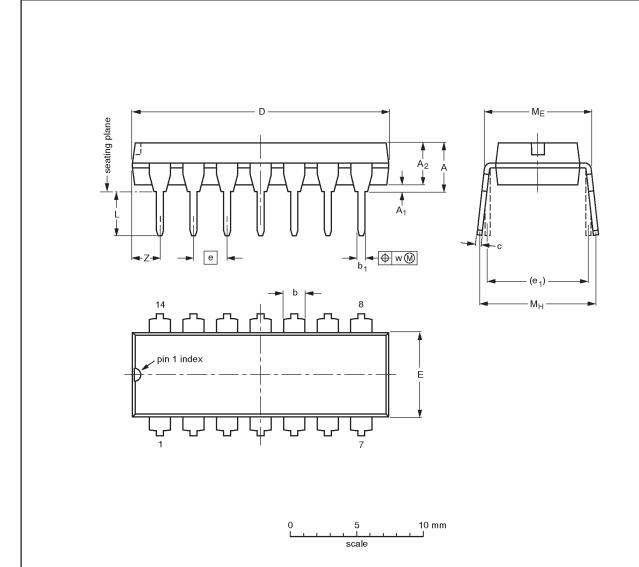
Philips Semiconductors Product specification

Dual 4-input NAND gate

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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

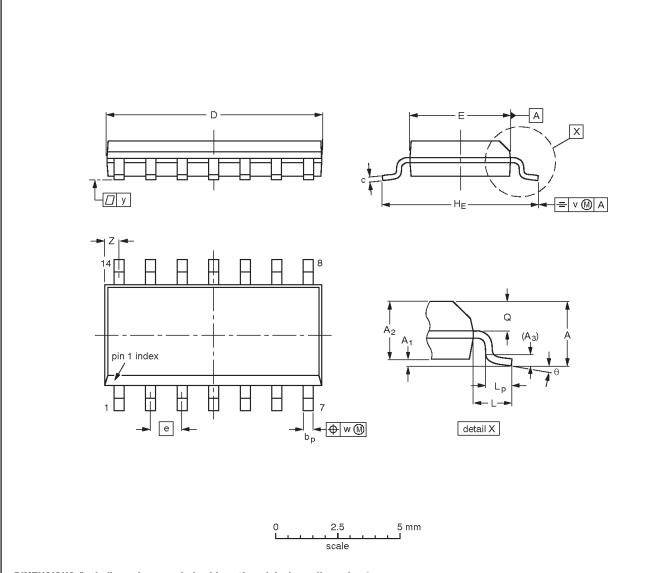
OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11	

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SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075		0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT108-1	076E06S	MS-012AB				95-01-23 97-05-22

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Dual 4-input NAND gate

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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